PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2611073

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TONY S. CRUZ-URIBE	06/24/2011
JOSEPH E. SCHEFFELIN	06/25/2011
TSUYOSHI YAMASHITA	06/28/2011
SILAM J. CHOY	06/24/2011

RECEIVING PARTY DATA

Name:	Hewlett-Packard Development Company, L.P.
Street Address:	11445 Compaq Center Drive West
City:	Houston
State/Country:	TEXAS
Postal Code:	77070

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14117053

CH $40.00 14117053

CORRESPONDENCE DATA

Fax Number: (970)778-4063
Phone: (541)715-8443
Email: pto.assignments@hp.com
Correspondence will be sent via US Mail when the email attempt is unsuccessful.
Correspondent Name: HEWLETT-PACKARD COMPANY
Address Line 1: 3404 E. HARMONY ROAD MS 35
Address Line 2: INTELLECTUAL PROPERTY ADMINISTRATION
Address Line 4: FORT COLLINS, COLORADO 80528

NAME OF SUBMITTER:	TERRI WALKER
Signature:	/Terri Walker/

Date:	11/12/2013

Total Attachments: 4
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HEWLETT-PACKARD COMPANY
Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

PATENT REFERENCE: 700205733

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each) have agreed and hereby agree to assign to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPDC), in furtherance of my/our obligations to the Hewlett-Packard Company and its subsidiaries and affiliates, and do hereby assign and transfer to HPDC, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

PIEZOELECTRIC INKJET DIE STACK

Filing Date: June 29, 2011 **Application No.:** PCT/US2011/042265

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

I/we additionally authorize HPDC to file applications in my/our name for Letters Patent in any country, to be held and enjoyed by HPDC, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC,

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.

Tony S. Cruz-Uribe
Inventor's Signature

6-24-2011
Date Assignment Signed

Tony S. Cruz-Uribe
Inventor's Typed Name

6-24-2011
Date Application Signed

Inventor's Signature

Date Assignment Signed

Joseph E. Scheffelin
Inventor's Typed Name

Date Application Signed

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Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

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PIEZOELECTRIC INKJET DIE STACK

Filing Date: ______ **Application No.:** ______

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

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AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to HPDC, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPDC, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPDC, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPDC;

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to HPDC, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.

Inventor's Signature ______ Date Assignment Signed ______

Tony S. Cruz-Uribe
Inventor's Typed Name ______ Date Application Signed ______

Inventor's Signature ______ Date Assignment Signed: 6/24/11

Joseph E. Scheffelin
Inventor's Typed Name ______ Date Application Signed: 6/28/11

HEWLETT-PACKARD COMPANY
Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

PATENT REFERENCE: 700205733

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature	6/28/2011 Date Assignment Signed
Tsuyoshi Yamashita Inventor's Typed Name	6/28/2011 Date Application Signed
Inventor's Signature	Date Assignment Signed
Silam J. Choy Inventor's Typed Name	Date Application Signed
Inventor's Signature	Date Assignment Signed
Inventor's Typed Name	Date Application Signed
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PATENT APPLICATION

PATENT REFERENCE: 700205733

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature

Date Assignment Signed

Tsuyoshi Yamashita

Inventor's Typed Name

Date Application Signed

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6/24/2011

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Inventor's Typed Name

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